

## REMARKS

The Examiner's Action mailed on November 20, 2003, has been received and its contents carefully considered. Additionally attached to this Amendment, is a Petition for an Extension of Time, extending the period for response to March 20, 2004, as well as a Request for Continued Examination (RCE), together with the appropriate fees.

In this Amendment, independent claim 7 has been amended. Claim 7 is the only claim pending in the application. For at least the following reasons, it is submitted that this application is in condition for allowance.

Initially, Applicant would like to take this opportunity to thank the Examiner for granting the various interviews conducted on March 11 and March 12, 2004. During these interviews, agreement was reached that claim 7, as currently amended, is patentably distinguishable over the various cited references. Thus, it was agreed that the Examiner's rejections would be withdrawn, since the applied reference does not disclose or suggest that the warp preventing board thickness is substantially equal to the wiring board thickness, nor that the warp preventing board and the wiring board are fabricated from an identical material. Moreover, and as further discussed with the Examiner, none of the cited references disclose or suggest a warp preventing board that has a coefficient of thermal expansion that is essentially equal to a coefficient of thermal expansion of the wiring board, or a semiconductor chip that has a coefficient of thermal expansion that is different from the coefficient of thermal expansion of the warp preventing board and the wiring board, or that the warp preventing board and the wiring board collectively cause any thermal expansion and thermal contraction to occur essentially equally on both the first semiconductor chip surface and the second

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semiconductor chip surface thereby preventing warpage of the semiconductor chip during a change in an environmental temperature, as amended into claim 7. It is thus requested that this claim be allowed.

It is submitted that this application is in condition for allowance. Such action and the passing of this case to issue are requested.

Should the Examiner feel that a further conference would help to expedite the prosecution of the application, the Examiner is hereby invited to contact the undersigned counsel to arrange for such an interview.

Respectfully submitted,

March 18, 2004  
Date

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